

#### US005773083A

# United States Patent [19]

## Fischer et al.

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[54]	METHOD FOR COATING A SUBSTRATE WITH A COATING SOLUTION			
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[63]	Continuation of Ser. No. 693,468, Aug. 2, 1996, abandoned			
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[52]	<b>U.S. Cl. 427/240</b> ; 427/385.5; 427/231			

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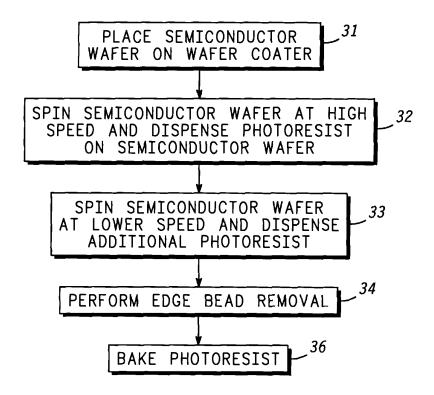
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### [57] ABSTRACT

A method for coating a substrate with a coating solution. In a first step (31), a semiconductor wafer is placed on a turntable. In a second step (32), the substrate is spun at a high speed and a coating solution is dispensed onto the substrate. In a third step (33), the turntable is spun at a low speed and additional coating solution is dispensed onto the substrate.

### 16 Claims, 2 Drawing Sheets



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